Variant: 001

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PMP7391 REV C Bill of Materials



Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description Description	PackageReference
2	!PCB1 C2, C4	2	0.047uF	PMP7391 GRM32DR72J473KW01L	Any MuRata	Printed Circuit Board CAP, CERM, 0.047 μF, 630 V, +/- 10%, X7R, 1210	1210
3	C3	1	100uF	ESMQ451VSN101MP25S	Chemi-Con	CAP, AL, 100 µF, 450 V, +/- 20%, TH	Cap 22x25mm
4	C5, C9, C12	3	0.1uF	GRM188R61E104KA01D	MuRata	CAP, CERM, 0.1 μF, 25 V, +/- 10%, X5R, 0603	0603
5	C6	1	680uF	EKZE350ELL681MK20S	Chemi-Con	CAP, AL, 680 µF, 35 V, +/- 20%, 0.021 ohm, TH	D12.5xL20mm
6	C7, C15	2	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0603	0603
7	C8, C19	2	1uF	GRM31MR71H105KA88L	MuRata	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 1206	1206
8	C11	1	0.01uF	GRM21BR72E103KW03L	MuRata	CAP, CERM, 0.01 µF, 250 V, +/- 10%, X7R, 0805	0805
9	C13	1	2200pF	DE2E3KY222MA2BM01	MuRata	CAP, CERM, 2200pF, 250V, +/-20%, KY, Radial D8x5mm	Radial D8x5mm
10	C14	1	470pF	GRM1885C1H471JA01D	MuRata	CAP, CERM, 470 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
11	C16	1	10uF	GRM31CR71E106KA12L	MuRata	CAP, CERM, 10 µF, 25 V, +/- 10%, X7R, 1206	1206
12	C17	1	0.022uF	GRM188R61H223KA01D	MuRata	CAP, CERM, 0.022 µF, 50 V, +/- 10%, X5R, 0603	0603
13	C18	1	1000pF	GRM188R71E102KA01D	MuRata	CAP, CERM, 1000 pF, 25 V, +/- 10%, X7R, 0603	0603
14	D5, D12	2	1000pr	BAV99,215	NXP Semiconductor	Diode, Switching, 100 V, 0.215 A, SOT-23	SOT-23
15	D6 D6	1	150V	MBR20H150CTG	ON Semiconductor	Diode, Schottky, 150 V, 10 A, TH	TO-220AB
16	D7, D10	2	30V	BAT54T1G	ON Semiconductor	Diode, Schottky, 30 V, 0.2 A, SOD-123	SOD-123
17	D8	1	100V	VS-43CTQ100PBF	Vishay-Semiconductor	Diode, Schottky, 100 V, 20 A, TH	TO-220AB
18	D9	1	200V	MURA120T3G	ON Semiconductor	Diode, Ultrafast, 200 V, 1 A, SMA	SMA
	D11						
19		1	100V	SMCJ100A	Littelfuse	Diode, TVS, Uni, 100 V, 1500 W, SMC	SMC
20	H1, H2, H3	3		634-10ABP	Wakefield Solutions	Heat Sink, TO-220, TH	16.26x25.4x16.26 mm
21	J1	1	2x1	1727010	Phoenix Contact	Conn Term Block, 2POS, 3.81mm, TH	2POS Terminal Block
22	L1	1	100uH	G044097	GCI Technologies	Inductor, Toroid, 100 µH, 6 A, 0.02 ohm, TH	D27.9xH16.76mm
23	Q1	1	800V	SPP02N80C3	Infineon Technologies	MOSFET, N-CH, 800 V, 2 A, TO-220AB	TO-220AB
24	Q2, Q6	2	60 V	MMBT2907ALT1G	ON Semiconductor	Transistor, PNP, 60 V, 0.6 A, SOT-23	SOT-23
25	Q2, Q6 Q4	1	40 V	MMBT2222ALT1G	ON Semiconductor	Transistor, NPN, 40 V, 0.6 A, SOT-23	SOT-23
26	Q5	1	900V	IPP90R1K2C3	Infineon Technologies	MOSFET, N-CH, 900 V, 5.1 A, TO-220AB	TO-220AB
26	R3, R18	2	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.1 W, 0603	0603
28	R4	1	3.3	CRCW08053R30JNEA	Vishay-Dale Vishay-Dale	RES, 1.00 K, 1%, 0.1 W, 0603 RES, 3.3, 5%, 0.125 W, 0805	0805
	R5, R6, R7		680	CRCW06053R30JNEA CRCW2512680RJNEG			2512
29		3	464k	CRCW2512660KJNEG	Vishay-Dale	RES, 680, 5%, 1 W, 2512	
30	R8, R9, R10, R11, R13, R14	6			Vishay-Dale	RES, 464 k, 1%, 0.25 W, 1206	1206
31	R15	1	4.7	CRCW08054R70JNEA	Vishay-Dale	RES, 4.7, 5%, 0.125 W, 0805	0805
32	R19	1	0.2	CSRN2010FKR200	Stackpole Electronics Inc	RES, 0.2, 1%, 1 W, 2010	2010
33	R22	1	301k	CRCW0603301KFKEA	Vishay-Dale	RES, 301 k, 1%, 0.1 W, 0603	0603
34	R23	1	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9 k, 1%, 0.1 W, 0603	0603
35	R25, R30, R100	3	4.99k	CRCW06034K99FKEA	Vishay-Dale	RES, 4.99 k, 1%, 0.1 W, 0603	0603
36	R26	1	4.12k	CRCW06034K12FKEA	Vishay-Dale	RES, 4.12 k, 1%, 0.1 W, 0603	0603
37	R27	1	17.4k	CRCW060317K4FKEA	Vishay-Dale	RES, 17.4 k, 1%, 0.1 W, 0603	0603
38	R28	1	150k	CRCW0603150KFKEA	Vishay-Dale	RES, 150 k, 1%, 0.1 W, 0603	0603
39	R29, R33	2	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
40	R31, R34	2	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
41	R32	1	21.5k	CRCW060321K5FKEA	Vishay-Dale	RES, 21.5 k, 1%, 0.1 W, 0603	0603
42	R35	1	2.49k	CRCW06032K49FKEA	Vishay-Dale	RES, 2.49 k, 1%, 0.1 W, 0603	0603
43	T1	1	1.5mH	G044050	GCI Technologies	Transformer, 1.5mH, TH	39x32mm
44	T2	1	300uH	G044052LF	GCI Technologies	Gate Drive Transformer, 300uH, TH	13.97x13.3x13.97mn
45	TP1, TP3, TP5	3	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
46	TP2, TP4, TP6	3	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
47	U3	1		UCC2894D	Texas Instruments	Active Clamp PWM Controller with Current Control, -40 to +85 degC, 16-	D0016A
						pin SOIC (D), Green (RoHS & no Sb/Br)	
48	U4	1		FOD817A	Fairchild Semiconductor	Optocoupler, 5 kV, 80-160% CTR, TH	DIP, 4-Leads, Body 6.86x4.83mm, Pitch 2.54mm
49	U5	1		TL431ACDBZR	Texas Instruments	degC, 3-pin SOT-23 (DBZ), Green (RoHS & no Sb/Br)	DBZ0003A
50	C1, C10	0	1uF	GRM155R61E105KA12D	MuRata	CAP, CERM, 1 μF, 25 V, +/- 10%, X5R, 0402	0402
51	D1, D4	0	75V	BAS16-7-F	Diodes Inc.	Diode, Ultrafast, 75 V, 0.3 A, SOT-23	SOT-23
52	D2	0	36V	BZT52C36-TP	Micro Commercial Components	Diode, Zener, 36 V, 500 mW, SOD-123	SOD-123
53	D3	0	12V	MMSZ5242B-7-F	Diodes Inc.	Diode, Zener, 12 V, 500 mW, SOD-123	SOD-123
54	Q3	0	100V	CSD19534Q5A	Texas Instruments	MOSFET, N-CH, 100 V, 10 A, SON 5x6mm	SON 5x6mm
55	Q7	0	150V	BSC190N15NS3 G	Infineon Technologies	MOSFET, N-CH, 150 V, 50 A, PG-TDSON-8	PG-TDSON-8
56	R1	0	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
57	R2, R21	0	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
58	R12	0	750k	CRCW0402750KFKED	Vishay-Dale	RES, 750 k, 1%, 0.063 W, 0402	0402
59	R16	0	562k	CRCW0402756KFKED	Vishay-Dale Vishay-Dale	RES, 562 k, 1%, 0.063 W, 0402	0402
60	R17	0	10.0k	CRCW0402302KFKED	Vishay-Dale Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
61	R20	0	37.4k	CRCW040210K0FKED	Vishay-Dale Vishay-Dale	RES, 37.4 k, 1%, 0.063 W, 0402	0402
62	U1	0	∪7.4K	UCC27511DBVR	Texas Instruments		DBV0006A
						and 8-A Peak Sink), DBV0006A	
63	U2	0	I	UCC24636DBVR	Texas Instruments	SYNCRONOUS RECTIFIER CONTROLLER WITH LOW POWER STANDBY, DBV0006A	DBV0006A

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